Product Information Sheet

EPO-TEK® OM118

Date:	September 2017		**Recommended Cure: 65°C / 1 Hour**
Rev:	III		
No. of Components:	Two		Minimum Alternative Cure(s):
Mix Ratio by Weight:	20 : 5		*May not achieve performance properties listed below*
Specific Gravity:	Part A: 1.18	Part B: 0.88	23°C / 24 Hours
Pot Life:	< 1 Hour		
Shelf Life- Bulk:	One year at room temperature		

NOTES:

- Container(s) should be kept closed when not in use.
- Filled systems should be stirred thoroughly before mixing and prior to use.
- Performance properties (rheology, conductivity, others) of the product may vary from those stated on the data sheet when bi-pak/syringe packaging or post-processing of any kind is performed. Epoxy's warranties shall not apply to any products that have been reprocessed or repackaged from Epoxy's delivered status/container into any other containers of any kind, including but not limited to syringes, bi-paks, cartridges, pouches, tubes, capsules, films or other packages.
- Syringe packaging will impact initial viscosity and effective pot life, potentially beyond stated parameters.
- *TOTAL MASS SHOULD NOT EXCEED 25 GRAMS*

Product Description: A two component, optically clear, electrically and thermally insulating epoxy designed for adhesive, sealing, and encapsulation applications found in semiconductor, medical, filtration and scientific/OEM industries. It is a slightly higher viscosity and Tg alternative to EPO-TEK® 301.

Typical Properties: Cure condition: 65°C / 1 Hour Different batches, conditions & applications yield differing results.
Data below is not guaranteed. To be used as a guide only, not as a specification. * denotes test on lot acceptance basis

PHYSICAL PROPERTIES:			
* Color (before cure):	Part A: Clear/colorless	Part B: Clear/colorless	
* Consistency:	Pourable liquid		
Viscosity (23°C) @ 100 rpm:	1,036	cPs	
Thixotropic Index:	N/A		
* Glass Transition Temp:	≥ 90	°C (Dynamic Cure: 20-200°C/ISO 25 Min; Ramp -10-200°C @20°C/Min)	
Coefficient of Thermal Expansion (CTE):			
Below Tg:	45	x 10^{-6} in/in°C	
Above Tg:	163	x 10^{-6} in/in°C	
Shore D Hardness:	81		
Lap Shear @ 23°C:	1,384	psi	
Die Shear @ 23°C:	≥ 10	Kg	3,556 psi
Degradation Temp:	419	°C	
Weight Loss:			
@ 200°C:	0.54	%	
@ 250°C:	0.62	%	
@ 300°C:	0.78	%	
Suggested Operating Temperature:	< 325	°C (Intermittent)	
Storage Modulus:	206,683	psi	
* Particle Size:	N/A		

OPTICAL PROPERTIES @ 23°C:		
Spectral Transmission:	> 95% @ 360-1640	nm
Refractive Index:	1.5465 @589	nm

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